

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on) \max}$	$I_D$ $T_A = +25^\circ\text{C}$
-50V	10Ω @ $V_{GS} = -5\text{V}$	-130mA

## Description

This MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

- General Purpose Interfacing Switch
- Power Management Functions
- Analog Switch

## Features and Benefits

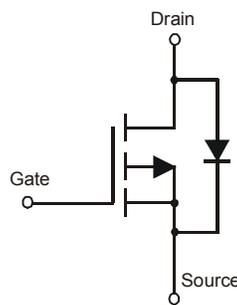
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

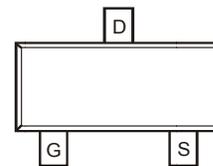
- Case: SOT23
- Case Material: UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish (Lead Free Plating) Solderable per MIL-STD-202, Method 208 **Ⓔ3**
- Terminal Connections: See Diagram
- Weight: 0.008 grams (approximate)



Top View



Equivalent Circuit



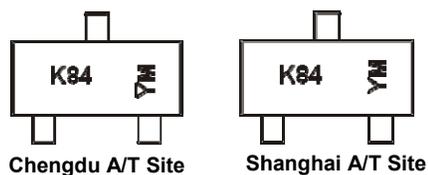
Top View

## Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BSS84-7-F	Commercial	SOT23	3000/Tape & Reel
BSS84Q-7-F	Automotive	SOT23	3000/Tape & Reel
BSS84-13-F	Commercial	SOT23	10000/Tape & Reel
BSS84Q-13-F	Automotive	SOT23	10000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

## Marking Information



K84 = Product Type Marking Code  
 YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)  
 YM = Date Code Marking for CAT (Chengdu Assembly/ Test site)  
 Y or  $\bar{Y}$  = Year (ex: A = 2013)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	...	2011	2012	2013	2014	2015	2016	2017
Code	J	K	L	M	N	P	R	...	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	$V_{DSS}$	-50	V
Drain-Gate Voltage $R_{GS} \leq 20\text{K}\Omega$	$V_{DGR}$	-50	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current (Note 5)	$I_D$	-130	mA
Pulsed Drain Current	$I_{DM}$	-1.2	A

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	$P_D$	300	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	-50	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current	$I_{DSS}$	—	—	-1	$\mu\text{A}$	$V_{DS} = -50\text{V}, V_{GS} = 0\text{V}, T_J = +25^\circ\text{C}$
		—	—	-2	$\mu\text{A}$	$V_{DS} = -50\text{V}, V_{GS} = 0\text{V}, T_J = +125^\circ\text{C}$
		—	—	-100	nA	$V_{DS} = -25\text{V}, V_{GS} = 0\text{V}, T_J = +25^\circ\text{C}$
Gate-Body Leakage	$I_{GSS}$	—	—	$\pm 10$	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS (Note 6)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	-0.8	—	-2.0	V	$V_{DS} = V_{GS}, I_D = -1\text{mA}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	—	10	$\Omega$	$V_{GS} = -5\text{V}, I_D = -0.100\text{A}$
Forward Transconductance	$g_{FS}$	0.05	—	—	S	$V_{DS} = -25\text{V}, I_D = -0.1\text{A}$
<b>DYNAMIC CHARACTERISTICS (Note 7)</b>						
Input Capacitance	$C_{iss}$	—	—	45	pF	$V_{DS} = -25\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	—	—	25	pF	
Reverse Transfer Capacitance	$C_{rss}$	—	—	12	pF	
<b>SWITCHING CHARACTERISTICS (Note 7)</b>						
Turn-On Delay Time	$t_{D(ON)}$	—	10	—	ns	$V_{DD} = -30\text{V}, I_D = -0.27\text{A},$
Turn-Off Delay Time	$t_{D(OFF)}$	—	18	—	ns	$R_{GEN} = 50\Omega, V_{GS} = -10\text{V}$

- Notes:
- Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing

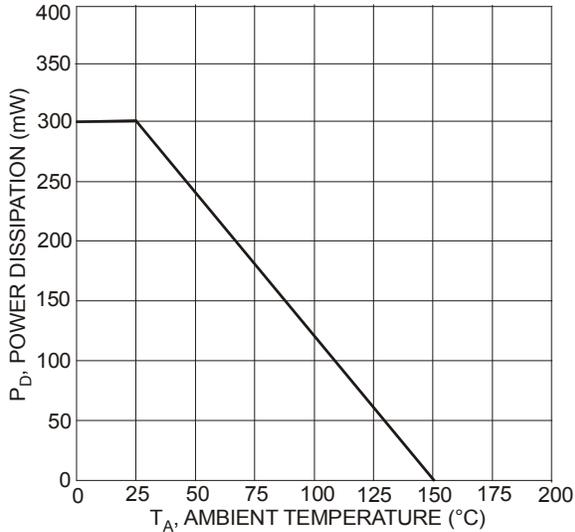


Fig. 1 Max Power Dissipation vs. Ambient Temperature

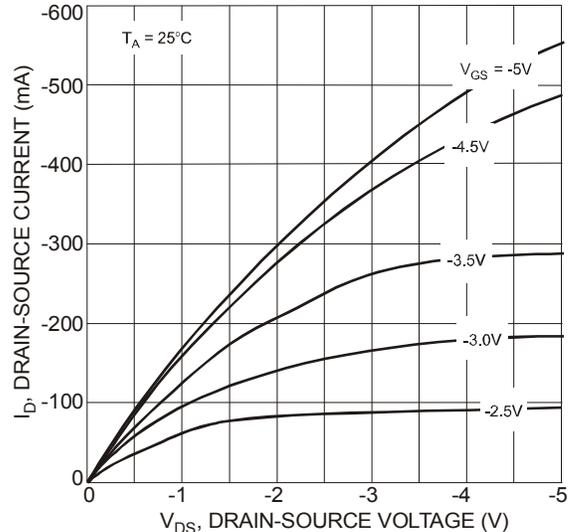


Fig. 2 Drain-Source Current vs. Drain-Source Voltage

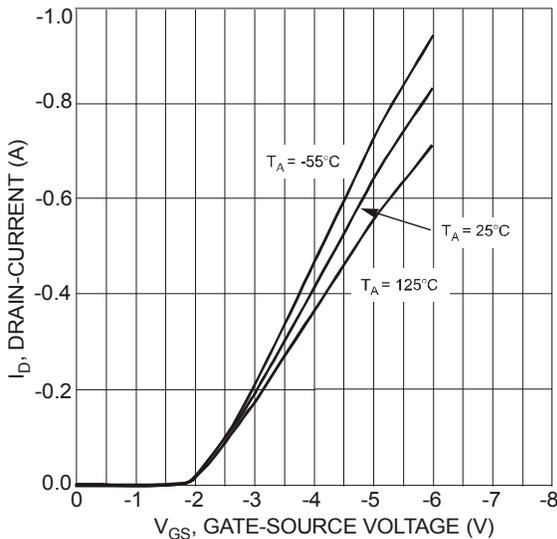


Fig. 3 Drain-Current vs. Gate-Source Voltage

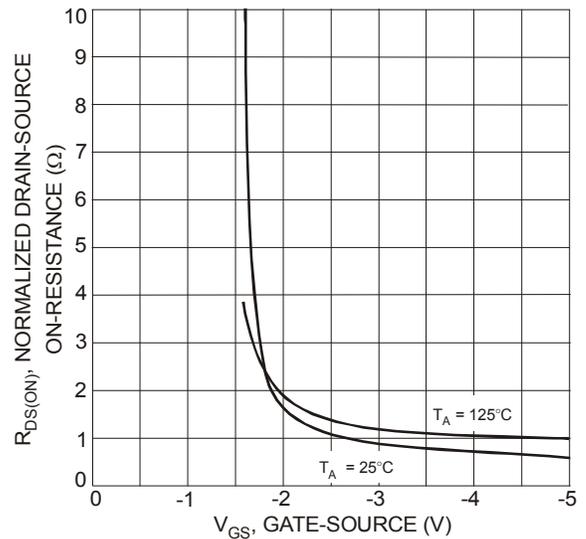


Fig. 4 On-Resistance vs. Gate-Source Voltage

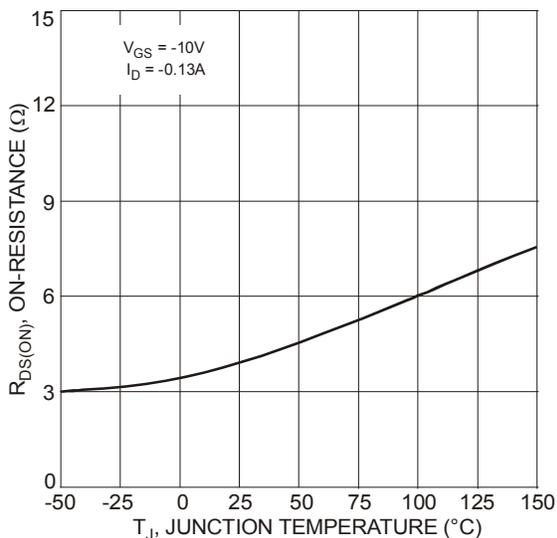


Fig. 5 On-Resistance vs. Junction Temperature

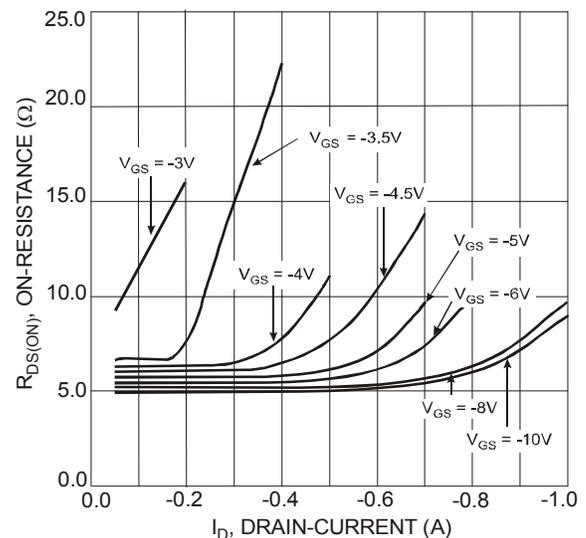
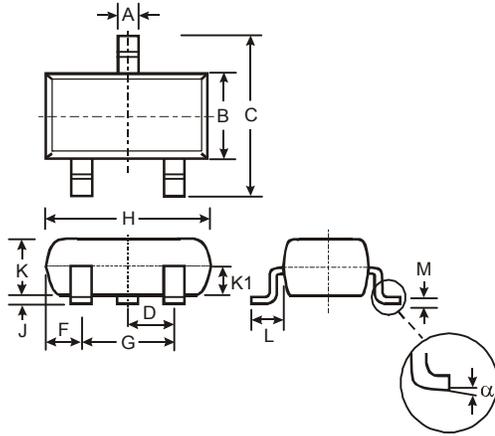


Fig. 6 On-Resistance vs. Drain-Current

**Package Outline Dimensions**

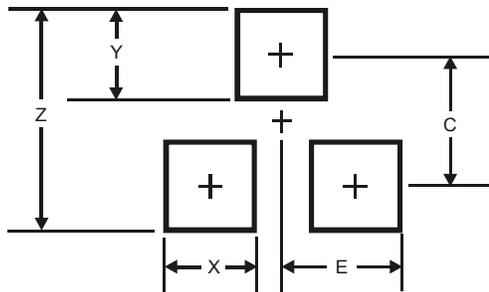
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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